

Date:2005/07/01

Corporate Headquarters:
FabI: No. 2, R&D Rd. VI,
FabII: No. 4, Creation Rd. III,
Science-Based Industrial Park, Hsinchu,
Taiwan 300, R.O.C
TEL: 886-35-770066
FAX: 886-35-774527(Fab I)
886-35-789467(Fab II)

SpiFlash[®] Memory Product Notification

Dear Valued Customer:

Thank you for your interest and support of NexFlash spiFlash[®] products.

Sales Office:
11Fl, No. 115, Sec. 3,
Min Sheng E. Rd., Taipei, Taiwan 105,
R.O.C.
TEL: 886-2-7190505
FAX: 886-2-7197502

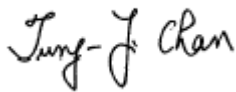
On June 23, 2005 Winbond Electronics Corporation acquired NexFlash Technologies, Inc. Winbond was NexFlash's fab partner before the acquisition so there will be no change in terms of the silicon wafers supply. For package, test and shipment, Winbond will maintain the same supply chain and shipping materials for most products through Q3 2005. Thus, there are only a few issues that may need your initial attention:

- 1) Please change your Vendor ID from NexFlash to Winbond.
- 2) Please note that Winbond "W" logo marking will gradually replace the NexFlash "NX" logo on parts being delivered starting in September 2005. To simplify the transition process we request you allow acceptance of either logo. All other part number markings will remain the same.
- 3) Please note that a Winbond logo will be added to the inner box and shipping carton in addition to the standard NexFlash packaging and labeling.

Winbond will continue to support ordering of the existing NexFlash part numbers beginning with the NX prefix. We have enclosed a mapping table of NexFlash "NX" part numbers (existing) to the new Winbond "W" part numbers (future). At this time, either number can be used for placing orders. We recommend using the "W" part numbers for all new projects.

Winbond's mission is to continually provide customers with excellent and high quality products. If you have any questions or requests regarding our spiFlash[™] products, please feel free to contact us at any time. Winbond looks forward to supporting your future Serial Flash needs.

Sincerely yours,



Tung-Yi Chan
Vice President of Sales
Winbond Electronics Corporation

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Part Number Mapping Table

Sales Office:
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	Ordering Part Number		
	NexFlash (existing)	Winbond (future)	Shape
1M	NX25P10-VNI	W25P10VSNI	E
	NX25P10-VNI-G	W25P10VSNIG	E
	NX25P10-VNI-T	W25P10VSNI	T
	NX25P10-VNI-GT	W25P10VSNIG	T
2M	NX25P20-VNI	W25P20VSNI	E
	NX25P20-VNI-G	W25P20VSNIG	E
	NX25P20-VNI-T	W25P20VSNI	T
	NX25P20-VNI-GT	W25P20VSNIG	T
4M uniform sector	NX25P40-VNI	W25P40VSNI	E
	NX25P40-VNI-G	W25P40VSNIG	E
	NX25P40-VNI-T	W25P40VSNI	T
	NX25P40-VNI-GT	W25P40VSNIG	T
4M boot block	NX25B40-VNI-G	W25B40VSNIG	E
	NX25B40-VNI-GT	W25B40VSNIG	T
	NX25B40A-VNI-G	W25B40AVSNIG	E
	NX25B40A-VNI-GT	W25B40AVSNIG	T
8M	NX25P80-VSI-G	W25P80VSSIG	E
	NX25P80-VSI-GT	W25P80VSSIG	T
	NX25P16-VSI-G	W25P16VSSIG	E
	NX25P16-VSI-GT	W25P16VSSIG	T
	NX25P16-VFI-G	W25P16VSFIG	E
	NX25P16-VFI-GT	W25P16VSFIG	T